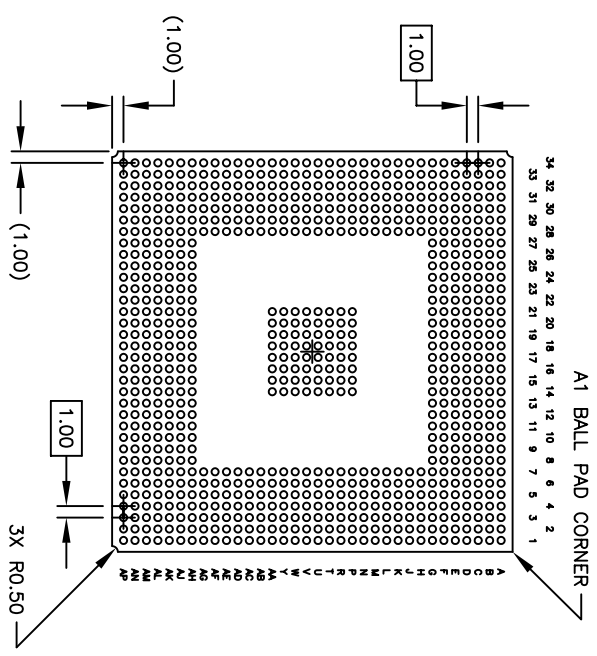
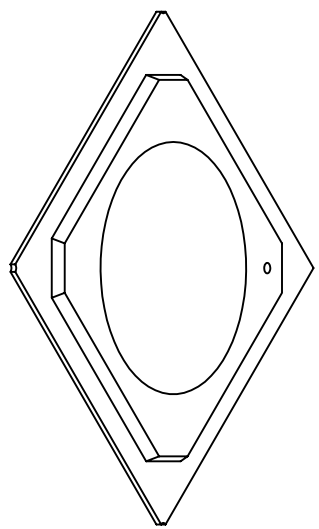


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	01/23/04	P.PAIK
01	COMBINE PAD & LAND PATTERN	06/20/13	KS

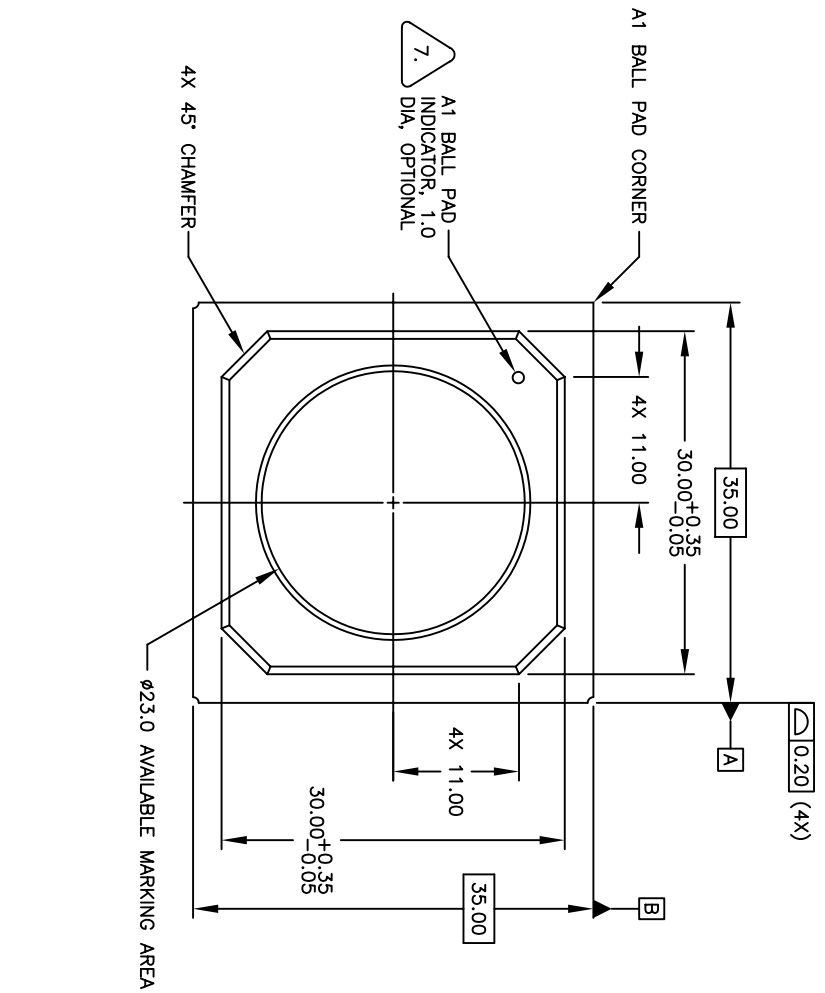


**BOTTOM VIEW**  
820 SOLDER BALLS

- NOTES: UNLESS OTHERWISE SPECIFIED
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
  2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.
  3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 34 X 34.
  4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 1156.
  5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
  6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
  7. A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK. AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.
  8. REFERENCE SPECIFICATIONS:  
A. AAWW SPEC #001-0531-2234; PACKING OPERATION PROCEDURE.  
B. AAWW SPEC #001-0519-2062; MARKING.  
C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION AAR-1.

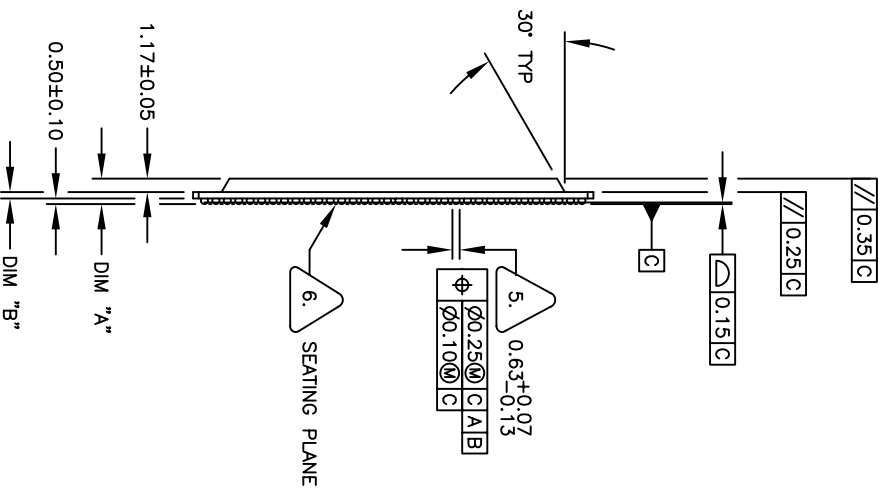
TOLERANCES UNLESS SPECIFIED		IDT	
DECIMAL	ANGULAR	www.idt.com	
X.XX ± 0.1	± 1°	San Jose, CA 95138	
X.XXX ± 0.05		PHONE: (408) 284-8200	
X.XXXX ± 0.020		FAX: (408) 492-8674	
APPROVALS	DATE	TITLE	
DRAWN <i>DPG/P</i>	01/16/04	BH 820 PACKAGE OUTLINE	
CHECKED		35 x 35 mm BODY	
		1.0 mm PITCH TEPBGA	
SIZE	DRAWING No.	REV	
C	PSC-4127	01	
DO NOT SCALE DRAWING		SHEET 1 OF 3	

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	01/23/04	P.PAIK
01	COMBINE POD & LAND PATTERN	06/20/13	KS



TOP VIEW

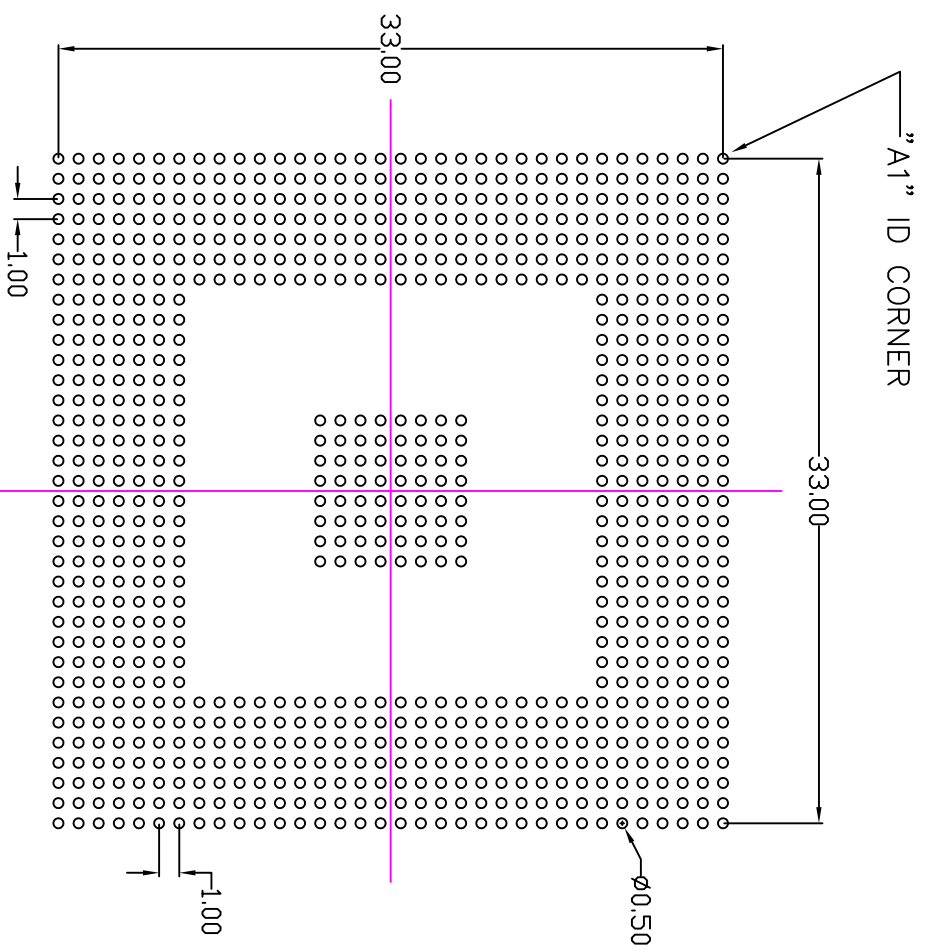
NO. LAYERS	DIM "A"	DIM "B"	STANDARD	NOTES
4	2.23±0.21	0.56±0.06	STANDARD	
TEPBGA-2 THICKNESS SCHEDULE				



SIDE VIEW

TOLERANCES UNLESS SPECIFIED	
DECIMAL	ANGULAR
X.XX ± 0.1	± 1°
X.XXX ± 0.05	
X.XXXX ± 0.030	
APPROVALS	DATE
DRAWN: <i>Dyca</i>	01/16/04
CHECKED	
<b>IDT</b> 6024 SILVER CREEK VALLEY ROAD San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 492-8674	
TITLE: BH 820 PACKAGE OUTLINE	
35 x 35 mm BODY	
1.0 mm PITCH TEPBGA	
SIZE: C	DRAWING No: PSC-4127
DO NOT SCALE DRAWING	SHEET 2 OF 3

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	01/23/04	P.PAIK
01	COMBINE PAD & LAND PATTERN	06/20/13	KS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		DECIMAL ANGULAR	
XXXX ± 0.05	± 1°		
XXXXX ± 0.030			
APPROVALS	DATE	TITLE	
DRAWN <i>PXP</i>	01/16/04	BH 820 PACKAGE OUTLINE	
CHECKED		35 x 35 mm BODY	
		1.0 mm PITCH TEPBGA	
		SIZE C	REV 01
		DRAWING NO. PSC-4127	
		DO NOT SCALE DRAWING	SHEET 3 OF 3

**IDT** 6024 SILVER CREEK VALLEY ROAD  
 San Jose, CA 95138  
 PHONE: (408) 284-8200  
 FAX: (408) 492-8674  
 www.IDT.com